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(54) METHOD OF REMOVING PROTECTING FILM
FROM SEMICONDUCTOR WAFER

(57) Abstract:

PURPOSE: To make it possible to perform continuous releasing and removal end to improve working efficiency by automatically releasing a protecting film which is stuck to the circuit-pattern forming surface of a semiconductor wafer through a releasing tape with a releasing mechanism.

CONSTITUTION: A releasing tape is bonded to a protecting film 3. An adhesive agent 2 is used for bonding. The adhesive strength is set so that the strength is higher than the adhesive strength of the protecting film 3 to the circuit pattern forming surface of a semiconductor wafer 5. In this way, the protecting film 3 which

is stuck to the circuit-pattern forming surface can be released and removed from the circuit-pattern forming surface through the releasing tape 1 which is bonded to the protecting film 3. The releasing tape 1 is formed with a base material whose surface resistivity on at least one surface is $10^8 \Omega/\text{cm}^2$. Therefore, the generation of static electricity when the protecting film 3 is released and removed is prevented or decreased based on the conductivity of the film, and the breakdown of the circuits can be prevented.

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